

WHAT IS CLAIMED IS:

1. A packaged die comprising:
 - 5 a die pad having a die having an electrical circuit thereon attached thereto;
 - a plurality of leads arranged around said die pad, at least one of said leads being connected to said die;
 - 10 a power ring comprising a conductor disposed between said leads and said die pad, at least one power connection on said die being connected to said power ring; and
 - 15 a layer of encapsulating material covering said die, said die pad, said power ring, and said leads, said layer having a top surface, a bottom surface, and side surfaces, wherein each of said leads comprises a conductor having a portion thereof exposed on said bottom surface and wherein a portion of said conductor in said power ring is exposed on said bottom surface.
2. The packaged die of Claim 1 wherein said exposed portions of said conductors further comprise solder balls.
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 3. The packaged die of Claim 1 wherein said die pad, said leads, and said power ring each extend to at least one of said side surfaces.
 4. The packaged die of Claim 1 wherein each of said leads comprises a conductor
 - 25 having a portion thereof that is not exposed on said bottom surface and wherein a portion of said conductor in said power ring is not exposed on said bottom surface.